

2STD1665

Low voltage fast-switching NPN power transistor

General features

- Very low collector to emitter saturation volatage
- High current gain characteristic fast-switching speed
- Through-hole IPAK (TO-251) power package in tube (suffix"-1")
- Surface mounting DPAK (TO-252) power package in tape & reel (suffix"T4")

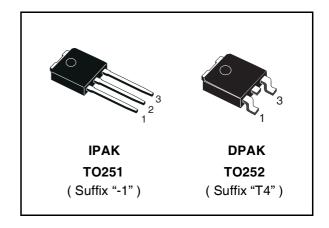
Applications

- Ccfl drivers
- Voltage regulators
- Relay drivers
- High efficiency low voltage switching applications

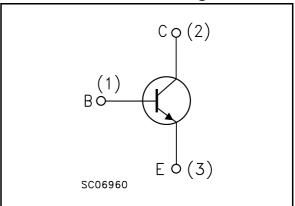
Description

The device is manufactured in NPN Planar Technology by using a "Base Island" layout.

The resulting transistor shows exceptional high gain performance coupled with very low saturation voltage.



Internal schematic diagrams



Order codes

Part Number	Marking	Package	Packing
2STD1665T4	D1665	DPAK	Tape & reel
2STD1665-1	D1665	IPAK	Tube

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1 Electrical ratings

Table 1. Absolute maximum rating

Symbol	Parameter	Value	Unit
V _{CBO}	Collector-base voltage (I _E = 0)	150	V
V _{CEO}	Collector-emitter voltage (I _B = 0)	65	V
V _{EBO}	Emitter-base voltage ($I_C = 0$)	7	V
I _C	Collector current	6	Α
I _{CM}	Collector peak current (t _P < 5ms)	20	Α
I _B	Base current	1	Α
P _{tot}	Total dissipation at T _c = 25°C	15	W
T _{stg}	Storage temperature	-65 to 150	°C
TJ	Max. operating junction temperature	150	°C

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R _{thj-amb}	Thermal resistance junction-amb max	8.33	°C/W

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2 Electrical characteristics

 $(T_{case} = 25^{\circ}C \text{ unless otherwise specified})$

Table 3. Electrical characteristics

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
I _{CBO}	Collector cut-off current $(I_E = 0)$	$V_{CB} = 120V$ $V_{CB} = 120V$	T _J = 100°C			50 1	nA μA
I _{EBO}	Emitter cut-off current $(I_C = 0)$	V _{EB} = 7V				10	nA
V _{(BR)CBO} (1)	Collector-base breakdown voltage (I _E = 0)	I _C = 100μA		150			V
V _{(BR)CEO} (1)	Collector-emitter breakdown voltage (I _B = 0)	I _C = 10mA		65			V
V _{(BR)EBO} (1)	Emitter-base breakdown voltage (I _C = 0)	I _E = 100μA		7			V
V _{CE(sat)} (1)	Collector-emitter saturation voltage	$I_{C} = 100 \text{mA}$ $I_{C} = 1 \text{A}$ $I_{C} = 2 \text{A}$ $I_{C} = 6 \text{A}$ $I_{C} = 6 \text{A}$	$I_B = 5mA$ $I_B = 50mA$ $I_B = 50mA$ $I_B = 150mA$ $I_B = 300mA$		50 70 140 290 320	350 380	>
V _{BE(sat)} (1)	Base-emitter saturation voltage	I _C = 4A	I _B = 200mA		1	1.15	٧
V _{BE(on)} (1)	Base-emitter On voltage	I _C = 4A	V _{CE} = 1V		0.89	1	V
h _{FE}	DC current gain	_	$V_{CE} = 1V$ $V_{CE} = 1V$ $V_{CE} = 1V$ $V_{CE} = 1V$	150 150 90 30	300 270 140 50	350	
C _{CBO}	Collector-base capacitance	V _{CB} = 10V	f = 1MHz		47		pF
	Resistive load				_		
t _{ON}	Turn-on time	$I_C = 3A$	$V_{CC} = 10V$		90		ns
t _s	Storage time	$I_{B1} = -I_{B2} = 0.3A$			800		ns
t _f	Fall time				90		ns

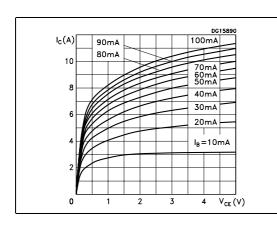
^{1.} Pulsed duration = 300 μ s, duty cycle \leq 1.5%.

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2.1 Electrical characteristics (curves)

Figure 1. Output characteristics

Figure 2. Derating Curve



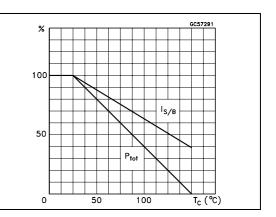
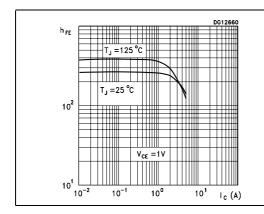


Figure 3. DC current gain

Figure 4. Collector-emitter saturation voltage



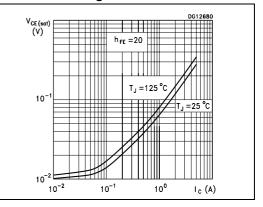
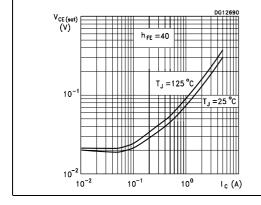
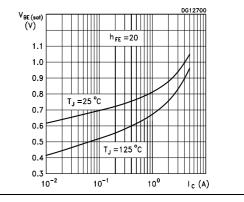


Figure 5. Collector-emitter saturation voltage

Figure 6. Base-emitter saturation voltage

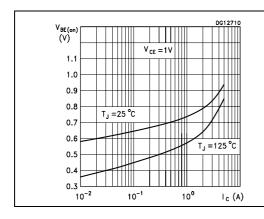




Electrical characteristics 2STD1665

Figure 7. Base-emitter on voltage

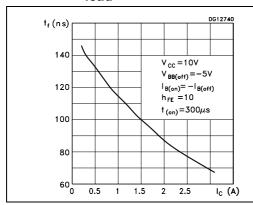
Figure 8. Switching times resistive load



DG12730 $t_s(ns)$ 2500 $V_{CC} = 1\overline{0V}$ $V_{BB(off)} = -5V$ $|_{B(on)} = -|_{B(off)}$ $|_{FE} = 10$ 2000 t_(on)=300µs 1500 1000 500 L 0.5 1 1.5 2 2.5 Ic (A)

Figure 9. Switching times resistive load

Figure 10. Switching times resistive load



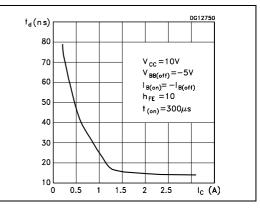
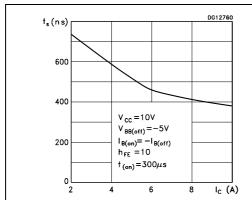
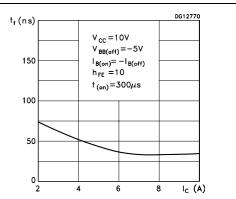


Figure 11. Switching times inductive load

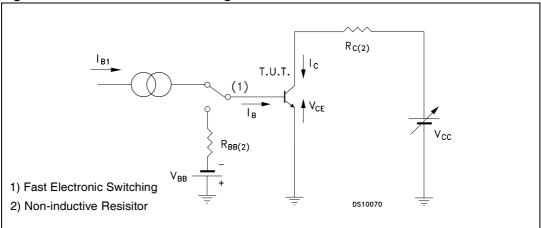
Figure 12. Switching times inductive load





2.2 Test circuits

Figure 13. Resistive load switching and RBSOA test circuit

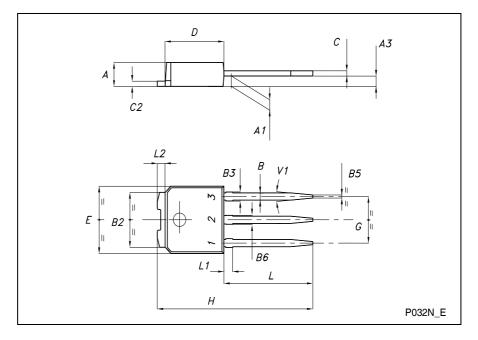


3 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com

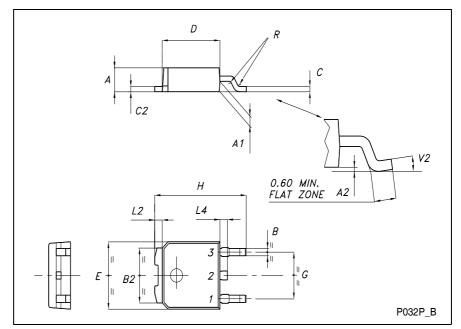
TO-251 (IPAK) MECHANICAL DATA

DIM.	mm			inch			
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Α	2.20		2.40	0.087		0.094	
A1	0.90		1.10	0.035		0.043	
А3	0.70		1.30	0.028		0.051	
В	0.64		0.90	0.025		0.035	
B2	5.20		5.40	0.204		0.213	
В3			0.85			0.033	
B5		0.30			0.012		
B6			0.95			0.037	
С	0.45		0.60	0.018		0.024	
C2	0.48		0.60	0.019		0.024	
D	6.00		6.20	0.237		0.244	
Е	6.40		6.60	0.252		0.260	
G	4.40		4.60	0.173		0.181	
Н	15.90		16.30	0.626		0.642	
L	9.00		9.40	0.354		0.370	
L1	0.80		1.20	0.031		0.047	
L2		0.80	1.00		0.031	0.039	
V1		10°			10°		



TO-252 (DPAK) MECHANICAL DATA

DIM.	mm			inch		
DIW.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α	2.20		2.40	0.087		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
В	0.64		0.90	0.025		0.035
B2	5.20		5.40	0.204		0.213
С	0.45		0.60	0.018		0.024
C2	0.48		0.60	0.019		0.024
D	6.00		6.20	0.236		0.244
Е	6.40		6.60	0.252		0.260
G	4.40		4.60	0.173		0.181
Н	9.35		10.10	0.368		0.398
L2		0.8			0.031	
L4	0.60		1.00	0.024		0.039
V2	0°		8°	0°		0°



4 Revision history

Table 4. Revision history

Date	Revision	Changes
08-May-2006	1	Initial release.

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